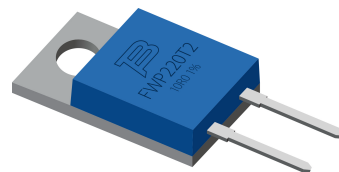


MATERIAL DECLARATION SHEET



Material Number	FWP220T Series			
Product Line	Fixed Resistors			
Compliance Date	2024/7/23			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Lead Plating	Tin Plating	2.64	Tin	7440-31-5	90.9	0.114	0.126
				Copper	7440-50-8	7.6	0.010	
				Silver	7440-22-4	2	0.002	
2	Leads	Copper Lead	100	Copper	7440-50-8	100	4.762	4.762
3	Inside Soldering	Tin Plating	5.28	Tin	7440-31-5	90.9	0.229	0.252
				Copper	7440-50-8	7.6	0.019	
				Silver	7440-22-4	2	0.004	
4	Heatsink	Copper Plate	1350	Copper	7440-50-8	100	64.28	64.28
5	Heatsink Plating	Nickel Plating	1	Nickel	7440-02-0	100	0.048	0.048
6	Chipbond	Filled Epoxy	40	Epoxy	25068-38-6	100	1.905	1.905

MATERIAL DECLARATION SHEET



7	Substrate	Aluminium	120	Aluminium	7429-90-5	100	5.714	5.714
8	Foilbond	Foilbond	11	Dimethylacetamide	127-19-5	100	0.524	0.524
9	Resistor Material	Manganin ^{R1}	68.22	Copper	7440-50-8	83.5	2.711	3.248
				Nickel	7440-02-0	2.9	0.095	
				Manganese	7439-96-5	13.6	0.442	
10	Cover	Silicone Based	2	Silicon	7440-21-3	100	0.095	0.095
11	Mold	Fortron 1140L4	400	Polyphenylensulfid	26125-40-6	100	19.046	19.046
			Total weight	2100.14				

This Document was updated on: 2024/7/23

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. Resistive material weight will be different based on the resistance value.
3. The weight of the core and coating material will differ based on the size.